



Product Content Sheet

Package family	SC89-3/6lead Lead-free	Picture of typical product, optional
Date	June 22, 2004	
Version	A	

Composition part	Material group	Materials	Test report	CAS if applicable	Average mass (weight-%)*	Sum (%)	Traces (PPM)
Nickel	Leadframe			7440-02-0	0.0001 g	3.33	37,080
Copper	Leadframe			7440-50-8	0.001 g	33.33	365,180
Silver	Leadframe			7440-22-4	0.000033 g	1.10	11,050
Tin	Leadframe			7440-31-5	0.000030 g	1.00	9,890
Silicon	Die			7440-21-3	0.00006 g	2.00	21,410
Aluminum	Die			7429-90-5	0.0000001 g	0.03	20
Gold	Die			7440-57-5	0.0000060 g	0.20	2,000
Gold	Bondwire			7440-57-5	0.00002 g	0.67	5820
Fused Silica	Encapsulant			60676-86-0	0.0011 g	36.67	379,410
Resin - Phenol	Encapsulant				0.00040 g	13.33	132,190
SbO2	Encapsulant			7440-36-0	0.000032 g	1.07	10,550
Carbon Black	Encapsulant			1333-86-4	0.0000040 g	0.13	1,320
Bromine	Encapsulant			10097-32-2	0.000008 g	0.27	2,640
Tin	Plating			7440-31-5	0.00006 g	2.0	21,500
Sum in total						100.00	

*)Related to package weight; weight in particular, see corresponding package weight list

**)Slug / wire / frame / terminal can be a combination for device leads

***)Utilized as flame retardant

Package Weight List			Important remarks :
Package Family	Pin Count	Weight(grams)	
SC75	3	0.003	
	Weight range:		
	Fluctuation margin:		
Company	Vishay Siliconix		
Address	2201 Laurelwood Dr Santa Clara, Ca 95054		
E-mail	Dave.macdonald@vishay.com		
Intrnet	www.vishay.com		

- 1) Traces are product parts, substances etc. that are below a percentage of 0.1% by weight. Higher limits are accepted if the substance or material is Legally regulated (see note no. 2).
- 2) Substances, materials etc. with possible harmful effects on Human beings and the environment are listed.
- 3) There are no risks for human beings and to the environment if products are properly used as designated. This shall not apply to risks caused during procedures for disposal etc.
- 4) All statements herein are based on our present knowledge. If our products are used properly, there are no risks to Human beings and/or the environment.



TO:

FROM:

SUBJECT: Warranty for Non-Inclusion of Hazardous Substances in Products

DATE: June 22, 2004

Dear Sir/Madam,

It is the policy of Vishay Siliconix to:

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, Distribution and operating systems with respect to their impact on the health and Safety of our employees and the public, as well as their impact on the environment.

It is of particular concern to control or eliminate the use of those substances with established hazardous properties.

With this objective we have reviewed our manufacturing processes and materials Against the following directives:

- a) 2000/53/EC End of Vehicle Life Directive (EVL)
- b) 2000/53/EC Annex II to End of Vehicle Life (EVL II)
- c) 2002/95/EC Restriction of the use of Hazardous Substances Directive (RoHS)
- d) 2002/96/EC Waste Electrical and Electronic Equipment (WEEE)
- e) Montreal Agreement (ODS material)

We hereby warrant and guarantee that the customer approved products supplied by our Company comply fully with these directives and do not and will not contain any of the Following substances

- Cadmium and cadmium compounds;
- PBB (polybromobiphenyl) category and PBDE (polybrominated biphenyl ethers)category;
- Pentabromodiphenyl ether (Penta BDE) and Octabromodiphenyl ether (OctaBDE);
- Chlorinated paraffin (chlorine flame retarding materials / plasticizers);
- Polychlorinated biphenyl (PCB) category;
- Polychlorinated naphthalene category;
- Organic tin compounds (Tributhyl tin category & Triphenyl tin category);
- Asbestos, and
- Azo compounds.



In making this warranty we use the following exemptions as outlined in EVL II & RoHS.

Materials and Components	Scope of Exemption	Expiration Date of Exemption	Vishay Function/Application
Solder in electronic Circuit boards and other Electric applications	Lead in high melting temperature type solders(i.e. tin-lead solder alloys containing more than 85% lead).	None announced	Internal Die Attach
Electrical components Which contain lead in a glass or ceramic matrix Compound, except glass In bulbs and glaze of Spark plugs.		None announced	Glass passivation at die level.

Material Declaration

Material Declaration reports on individual part numbers of product families are available using any of the following internationally recognized formats.

	Application	Reference Link
1.	End-Of-Life Vehicles(ELV) Reporting Guideline and Compliance Connect™ Tool	http:
2.	International Material Data System	http:

Lead Free Plating

The position of Vishay Siliconix regarding lead-free terminal plating has been published elsewhere. All products are available with a lead-free finish. Please Contact your Marketing or Customer Service Representative for details.

sign _____

name David MacDonald
 post and rank Technical Marketing Engineer
 Vishay Siliconix
 e-mail: Dave.macdonald@vishay.com